

◆ DESCRIPTION

The MT7402 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

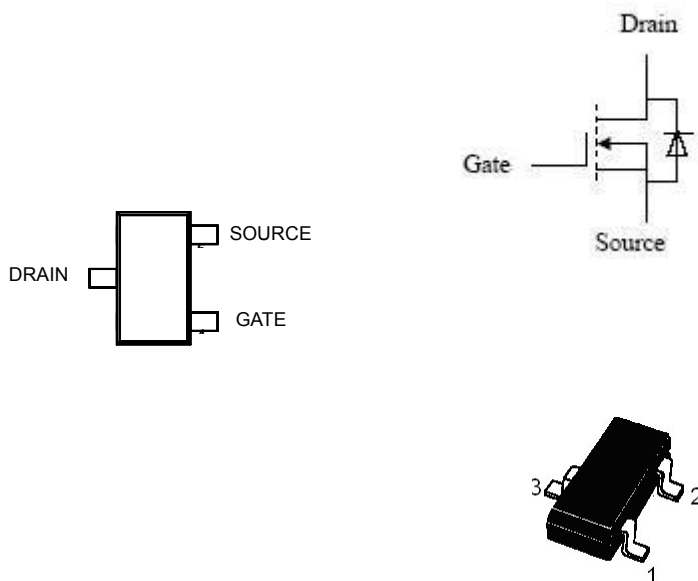
These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

◆ FEATURES

- 20V/4.0A,RDS(ON)=65mΩ@VGS=4.5V
- 20V/3.4A,RDS(ON)=80mΩ@VGS=2.5V
- 20V/2.8A,RDS(ON)=95mΩ@VGS=1.8V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- SOT-323 (SC-70-3L) package design

◆ APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

◆ PIN CONFIGURATION


◆ ABSOLUTE MAXIMUM RATINGS (Ta=25°C Unless Otherwise Noted)

SYMBOL	PARAMETER	MAXIMUM	UNITS
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D	Continuous Drain Current	T _C = 25°C	2.4
		T _C = 70°C	1.7
I _{DM}	Pulsed Drain Current	6	A
I _S	Continuous Source Current (Diode Conduction)	1.6	A
P _D	Power Dissipation	T _C = 25°C	1.19
		T _C = 70°C	0.76
T _J	Operating junction temperature range	-55 to 150	°C
T _{STG}	Storage temperature range	- 55 to 150	°C

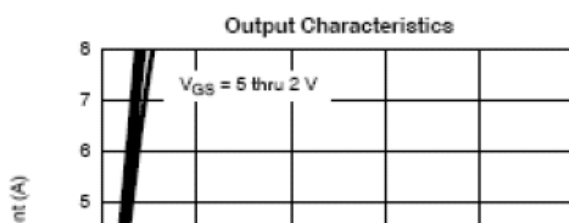
◆ THERMAL RESISTANCE RATINGS

Thermal Resistance	Symbol	Maximum	UNIT
Junction-to-Ambient	R _{θJA}	105	°C/W

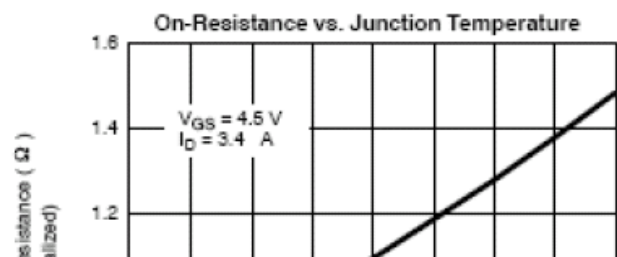
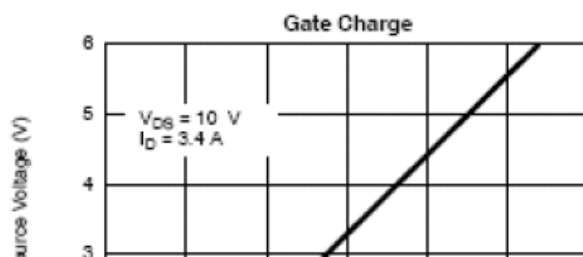
◆ ELECTRICAL CHARACTERISTICS: (Ta= 25°C Unless Otherwise Noted)

N- Channel Enhancement Mode MOSFET

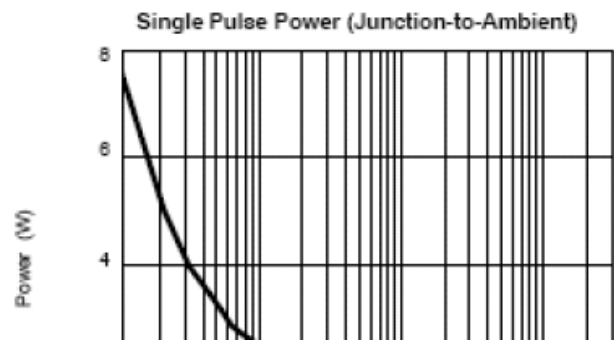
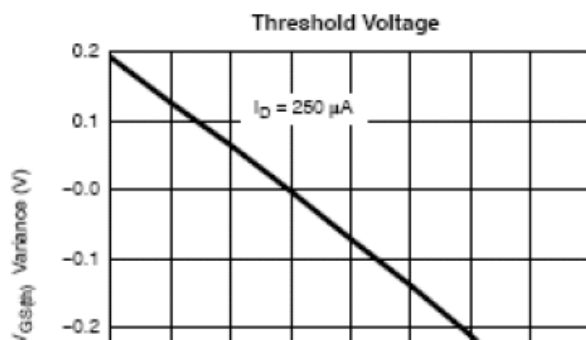
SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.35		0.85	V
I_{GSS}	Gate Leakage current	$V_{DS} = 0V, V_{GS} = \pm 12V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20V, V_{GS} = 0V$			1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55^\circ C$			5	
$I_{D(ON)}$	On-State Drain Current	$V_{DS} \leq 5V, V_{GS} = 4.5V$	6			A
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS} = 4.5V, I_D = 4.0A$		0.060	0.065	Ω
		$V_{GS} = 2.5V, I_D = 3.4A$		0.067	0.080	
		$V_{GS} = 1.8V, I_D = 2.8A$		0.076	0.095	
g_{fs}	Forward Transconductance	$V_{DS} = 5V, I_D = -3.6A$		10		S
V_{SD}	Diode Forward Voltage	$I_S = 1.6A, V_{GS} = 0V$		0.8	1.2	V
Dynamic Parameters						
C_{iss}	Input Cap.	$V_{DS} = 6V, V_{GS} = 0V$ $F = 1MHz$		485		pF
C_{oss}	Output Cap.			85		
C_{rss}	Reverse Transfer Cap.			40		
Q_g	Total Gate Charge	$V_{DS} = 6V, V_{GS} = 4.5V$ $I_D = 2.8A$		4.8	8	nC
Q_{gs}	Gate-Source Charge			1.0		
Q_{gd}	Gate-Drain Charge			1.0		
$t_{d(on)}$	Turn-On Time	$V_{DD} = 6V, R_L = 6\Omega$ $I_D = 1.0A, V_{GEN} = 4.5V$ $R_G = 6\Omega$		8	14	ns
t_r				12	18	
$T_{d(off)}$	Turn-Off Time			30	35	
t_f				12	16	

◆ TYPICAL CHARACTERISTICS


◆ **TYPICAL CHARACTERISTICS**



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◆ **SOT-323 PACKAGE OUTLINE**

